



200mA, 75V Switching SMD Diode

FEATURES

- Low power loss, high efficiency
- Ideal for automated placement
- High surge current capability
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

KEY PARAMETERS			
PARAMETER	VALUE	UNIT	
I _F	200	mA	
V _{RRM}	75	V	
V _F at I _F =150mA	1.25	V	
T _J Max.	150	°C	
Package	SOT-23		
Configuration	Single die		

APPLICATIONS

- Switching mode power supply (SMPS)
- Adapters
- Lighting application
- On-board DC/DC converter

MECHANICAL DATA

- Case: SOT-23
- Molding compound meets UL 94 V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 1A whisker test
- Weight: 8mg (approximately)





ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)				
PARAMETER	SYMBOL	BAS116	UNIT	
Marking code on the device		JV		
Power dissipation	P _D	225	mW	
Repetitive peak reverse voltage	V _{RRM}	75	V	
Mean forward current	Ι _ο	200	mA	
Non-Repetitive peak forward surge current @ t=1s	I _{FSM}	500	mA	
Thermal resistance (Junction to Ambient)(Note1)	$R_{\Theta JA}$	330	°C/W	
Junction temperature range	TJ	-55 to +150	°C	
Storage temperature range	T _{STG}	-55 to +150	°C	

Note1: Valid provided that electrodes are kept at ambient temperature



BAS116 Taiwan Semiconductor

ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	MIN	MAX	UNIT
Forward voltage	I _F = 1.0mA, T _J = 25°C		-	0.9	V
	I _F = 10mA, T _J = 25°C		-	1.0	
	I _F = 50mA, T _J = 25°C	V _F	-	1.1	
	I _F = 150mA, T _J = 25°C		-	1.25	
Reverse voltage	I _R =100μA, T _J = 25°C	V _R	75	-	V
Reverse current	V _R =75V T _J = 25°C		-	5	
	V_R =75V T _J = 150°C	-	80	nA	
Junction capacitance	f=1 MHz, V _R =0V	CJ	-	2.0	pF
Reverse recovery time	I _F =10mA, I _R =10mA, R _L =100Ω, I _{rr} =1mA	t _{rr}	-	3.0	μs

ORDERING INFORMATION			
ORDERING CODE	PACKAGE	PACKING	
BAS116 RF	SOT-23	3K / 7" Reel	
BAS116 RFG	SOT-23	3K / 7" Reel	

Note: "G" means green compound (halogen free)



CHARACTERISTICS CURVES

(T_A = 25°C unless otherwise noted)



Fig.1 Typical Forward Characteristics



Fig.2 Reverse Current vs.



Fig.3 Admissible Power Dissipation Curve



Fig.4 Typical Junction Capacitance



PACKAGE OUTLINE DIMENSION

SOT-23





SUGGESTED PAD LAYOUT



	DIM. Unit (mm) Min. Max.		Unit (inch)	
			Min.	Max.
A	0.89	1.12	0.035	0.044
b	0.30	0.50	0.012	0.020
с	0.08	0.20	0.003	0.008
D	2.80	3.04	0.110	0.120
E	2.10	2.64	0.083	0.104
E1	1.20	1.40	0.047	0.055
е	1.90 BSC		0.07	5 BSC
L1	0.54 REF.		0.021	I REF.

Symbol	Unit (mm)	Unit (inch)
A	1.00	0.039
В	0.85	0.033
С	2.10	0.083
D	3.10	0.122
E	0.98	0.039



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